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ABSTRACT

APPARATUS AND METHOD FOR MOUNTING COMPONENT

5 A component mounting system includes first to
third (pickup, transfer, and placement) stations. A
component supplied at the component supply is picked up by
a transport head at the pickup station and then transferred
to a placement head at the transfer station. The placement
head carries the component to the placement station where
the component is placed and mounted on a substrate such as
10 circuit board. The component held by the placement head is
recognized by an imaging device at or in the vicinity of
the transfer station.

Fig. 2